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Patent and Trademark Office s: Please Record the attached original documents or copy 2. Name and address of receiving party(ies): Name:
2. Name and address of receiving party(ies): Name: <u>Sony Corporation</u> Internal Address: <u>7-35, Kitashinagawa 6-chome</u> <u>Shinagawa-ku, Tokyo 141, Japan</u> Street Address: <u>City:</u> <u>State:</u> <u>Zip:</u> Additional Name(s) & Address(es) attached □ Yes ⊠ No APF - 9 2001 APF - 9 2001 B: Patent No.(s)
Name:Sony Corporation
7-35, Kitashinagawa 6-chome Shinagawa-ku, Tokyo 141, Japan Street Address:
7-35, Kitashinagawa 6-chome Shinagawa-ku, Tokyo 141, Japan Street Address:
Shinagawa-ku, Tokyo 141, Japan Street Address: City: State: Zip: Additional Name(s) & Address(es) attached □ Yes ⊠ No Image: Address (es) attached □ Yes ⊠ No Additional Name(s) & Address(es) attached □ Yes ⊠ No Image: Address (es) attached □ Yes (es) attach
City:State:Zip: Additional Name(s) & Address(es) attached □ Yes ⊠ No Additional Name(s) & Address(es) attached □ Yes ⊠ No APFi - 9 2001 LI LI pplication, the execution date of the application is:_ B: Patent No.(s)
Additional Name(s) & Address(es) attached Yes No APR - 9 2001 Explication, the execution date of the application is:_ B: Patent No.(s)
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B: Patent No.(s)
6. Total number of applications and patents involved
7. Total Fee (37 CFR 3.41 \$ 40.00
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Authorized to be charged to deposit account any
Additional fees
8. Deposit Account Number: 19.3140
(Attach duplicate copy of this page if paying by deposit account)
ng information is true and correct and any attached
April 5, 2001
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PATENT REEL: 011694 FRAME: 0368

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Docket Number:

09792909-4716

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INSPECTION APPARATUS AND METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention. said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration. the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignce of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention. applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/727,144_____, Filing Date:November 30, 2000

This assignment executed on the dates indicated below.

YUTAKA IMAI

Name of first or sole inventor TOKYO, JAPAN

Execution date of U.S. Patent Application

Residence of first or sole inventor

Signature of first or sqle inventor

March (J. 200] Date of this assignment

PATENT REEL: 011694 FRAME: 0369

Name of second inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN	
Residence of second inventor	
A. C.F.	
Signature of second inventor	May, 15,200/ Date of this assignment
Signature of Sciona Inventor	Date of this assignment
HITOSHI TAMADA	
Name of third inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of third inventor	
Hitzen Tomado	Mar. 15, 2001
Signature of third inventor	Date of this assignment
HIROYUKI WADA	
Name of fourth inventor	Execution date of U.S. Patent Application
KANAGAWA, JAPAN	
Residence of fourth inventor,	/
L'ANDAR TE AL	March 15,2001
Signature of fourth inventor	Date of this assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	

Signature of fifth inventor

AYUMU TAGUCHI

Date of this assignment

PATENT REEL: 011694 FRAME: 0370

RECORDED: 04/09/2001